



23rd IEEE European Test Symposium

Swissôtel Bremen

Bremen, Germany | May 28 – June 01, 2018

www.ets18.de



CALL FOR PAPERS

The IEEE European Test Symposium (ETS) is Europe's premier forum dedicated to presenting and discussing scientific results, emerging ideas, applications, hot topics, and new trends in the area of electronic-based circuit and system testing and reliability. In 2018, ETS will take place at Swissôtel, Bremen, Germany. It is organized by the University of Bremen, which co-sponsors the event jointly with the IEEE Council on Electronic Design Automation (CEDA). ETS traditionally enjoys a strong balance among academic and industrial participants. In addition to regular Scientific Papers, Special Sessions, Panels, and Embedded Tutorials, ETS features Vendor Sessions and Table-Top Demos as well as a special track on Emerging Test Strategies (ETS²) where new issues are presented by the industry and are discussed in an informal atmosphere. ETS is the major event of the European Test Week, which includes TSS (Test Spring School) and fringe workshops.

You are invited to participate and submit your contributions to ETS'18. The following topic chairs have been selected to put particular emphasis on their topic:

P. Bernardi: *Microprocessor and On-line Test*, K. Chakrabarty: *Emerging Technologies in Test*, P. Girard: *Power Issues in Test*, S. Hamdioui: *Memory and Nanotechnology Test*, E. Larsson: *Test Architectures and Standards*, G. Léger: *Analog/Mixed Signal Test*, M. Maniatakos: *Security and Trust Issues in Test*, I. Polian: *Test Generation and Reliability*, J. Rivoir: *Automatic Test Equipment and Yield*, C. Scholl: *Validation and Verification*, A. Singh: *Defect-based Test and Variability*.

In summary, areas of interest include (but are not limited to):

- Analog Test
- ATE Hardware and Software
- Automatic Test Generation
- Board Test and Diagnosis
- Boundary Scan Test
- Built-In Self-Test (BIST)
- Current-Based Test
- Defect-Based Test
- Delay and Performance Test
- Dependability and Functional Safety
- Design for Test (DfT)
- Design for Manufacturing (DfM)
- Diagnosis and Silicon Debug
- Economics of Test
- Test of Emerging Technologies
- Failure Analysis
- Fault Modeling and Simulation
- Fault Tolerance
- GPU Test
- High-Speed I/O Test
- Low-Power IC Test
- Memory Test and Repair
- MEMS Test
- Microprocessor Test
- Mixed-Signal Test
- Multi-/Many-core Processor Test
- Nanotechnology Test
- On-line Test
- Power Issues in Test
- Reconfigurable System Test
- Reliability
- RF Test
- Security and Trust Issues in Test
- Self-Repair
- Sensor Test
- Signal Integrity Test
- SiP, Stacked, 3D IC Test
- SoC Test
- Soft Errors
- Standards in Test
- Statistical Learning in Test
- Test Compression
- Test Quality
- Test Synthesis
- Thermal Issues in Test
- Validation and Verification
- Variability Issues in Test
- Yield Analysis and Enhancement

Publication – ETS'18 will produce electronic formal proceedings with ISBN number to be indexed in the IEEE Xplore Digital Library and other bibliographical search engines.

Submissions – ETS'18 seeks:

Scientific Papers for the Formal Proceedings, presenting novel, unpublished, and complete research work. Prospective authors should be aware that ETS'18 fully complies with the IEEE publication policies regarding multiple submissions, plagiarism, etc.

Key Dates for scientific papers:

Paper Submission Deadline:	December 4, 2017
Notification of acceptance:	February 13, 2018
Camera-ready manuscript:	March 18, 2018

ETS'18 also seeks proposals for:

- **Special Sessions, Panels, and Embedded Tutorials.**
 - Special Session contributions to the special track on **Emerging Test Strategies (ETS²)**.
 - **Vendor and Table-Top Demos presentations** focusing on new features of test related products.
 - **Fringe Workshops**, to be held during May 31 - June 01, 2018.
 - **Fringe Meetings**, to be held during the European Test Week.
- Key dates regarding the submission of proposals in the above categories can be found on the website.

Further Information:

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Paolo Bernardi (IT), Christoph Scholl (DE), Said Hamdioui (NL), Krish Chakrabarty (US), Patrick Girard (FR), Erik Larsson (SE), Gildas Léger (ES), Michael Maniatakos (AE), Adit Singh (US), Iliia Polian (DE), Jochen Rivoir (DE)

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Embedded Tutorial Chairs

Teresa McLaurin (US), Maria Michael (CY)

Special Session Chairs

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Industrial Relations Chairs

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Award Chairs

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ETS Fringe Workshops

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